REMARKS/ARGUMENTS

Claims 2-9 and 11-18 are pending in this application. The Examiner has withdrawn claim 9 from consideration. By this Amendment, Applicant AMENDS claims 2-9, CANCELS claims 1 and 10 and ADDS claims 11-18.

Applicant's counsel greatly appreciates the courtesies extended by the Examiner in the personal interview of August 2, 2004. In the personal interview, Applicant's counsel and the Examiner discussed the differences between the applied prior art and the present invention and potential amendments to the claims to overcome the prior art rejections. No agreement was reached with respect to the claims.

Applicant respectfully submits that claim 5 is generic. Since claim 9 depends upon generic claim 5, Applicant respectfully requests that the Examiner rejoin and allow claim 9 when claim 5 is allowed.

Claims 1-4, 6, 7 and 10 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of Kubota et al. (U.S. 5,644,107). Claim 8 was rejected under 35 U.S.C. 103(a) as being unpatentable over AAPA and Kubota et al., and further in view of Marusawa et al. (JP 9-294006). Claim 5 was rejected under 35 U.S.C. § 103(a) as being unpatentable over AAPA in view of Kubota et al. and Marusawa et al. (U.S. 5,498,999). Claims 1 and 10 have been canceled and claims 2, 4, 6, 7 and 9 have been amended to depend upon claim 5. Applicant respectfully traverses the rejections of claims 2-9.

Claim 5 has been amended to recite:

> "A method for manufacturing a center-electrode assembly comprising the steps of:
>
> forming through-holes in a ferrite mother board;
>
> alternately depositing a plurality of center-electrode patterns and a plurality of insulating films on the top surface of the ferrite mother board, the center-electrode patterns are formed by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method;
>
> forming a conductive pattern on the back surface of the ferrite mother board by at least one of a plating method, a printing method, a

sputtering method, a vapor deposition method, and a conductive paste applying method;

cutting a center-electrode assembly from the ferrite mother board by cutting the ferrite mother board at intervals of a predetermined size; and

forming connecting electrodes in the through-holes in the center electrode assembly by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method and a conductive paste applying method to electrically connect the center-electrode patterns formed on the top surface and the conductive pattern formed on the back surface; wherein

the plurality of center-electrode patterns and the plurality of insulating films are alternately deposited such that each of the plurality of center electrode patterns includes a portion that is in direct contact with a respective one of the plurality of insulating films and another portion that is in direct contact with the top surface of the ferrite mother board." (emphasis added)

Applicant's claim 5 recites the features of "the plurality of center-electrode patterns and the plurality of insulating films are alternately deposited such that each of the plurality of center electrode patterns includes a portion that is in direct contact with a respective one of the plurality of insulating films and another portion that is in direct contact with the top surface of the ferrite mother board." Claim 11 recites features that are similar to the features recited in claim 5, including the above-emphasized features. With the improved features and method steps of claims 5 and 11, Applicant has been able to provide a center-electrode assembly that has stable electrical characteristics, is easily handled, and is suitable for mass production and a manufacturing method therefor (see, for example, the paragraph bridging pages 2 and 3 of the originally filed Specification).

The Examiner acknowledged that AAPA and Kubota et al. fail to teach or suggest center-electrode patterns and a conductive pattern that are formed by a printing method. However, the Examiner alleged that Marusawa et al. teaches that conductor electrodes can be screen printed on a laminated magnetic body of a nonreciprocal

circuit device. Thus, the Examiner concluded that it would have been obvious "to have applied the conductors in the AAPA/Kubota combination device by screen-printing (such as taught by Marusawa) instead of punching, because it would have been considered a well-known art-recognized equivalent/alternative method for forming conductors on a ferrite board."

Claim 5 has been amended to recite the features of "the plurality of center-electrode patterns and the plurality of insulating films are alternately deposited such that each of the plurality of center electrode patterns includes a portion that is in direct contact with a respective one of the plurality of insulating films and another portion that is in direct contact with the top surface of the ferrite mother board." Claim 11 recites the features of "the center-electrode patterns and the insulating films are alternately disposed such that each of the center electrode patterns includes a portion that is in direct contact with a respective one of the insulating films and another portion that is in direct contact with the top surface of the ferrite mother board."

In contrast to the present claimed invention, Marusawa et al. (U.S. 5,498,999) teaches conductor patterns 8a, 8b, 9a, 9b, 10a, 10b which are formed on magnetic green sheets such that **every portion** of each of the conductor patterns 8a, 8b, 9a, 9b, 10a, 10b is in direct contact with **only** a magnetic green sheet. **None** of the conductor patterns of Marusawa et al. (U.S. 5,498,999) includes a portion that is in direct contact with a respective one of the plurality of insulating films and another portion that is in direct contact with the top surface of the ferrite mother board as recited in Applicant's claims 5 and 11. In fact, **none** of the conductor patterns of Marusawa et al. (U.S. 5,498,999) is in direct contact with any insulating film **or** in direct contact with the top surface of a ferrite mother board.

Accordingly, Applicant respectfully submits that Marusawa et al. (U.S. 5,498,999) clearly fails to teach or suggest the features of "the plurality of center-electrode patterns and the plurality of insulating films are alternately deposited such that each of the plurality of center electrode patterns includes a portion that is in direct contact with a

respective one of the plurality of insulating films and another portion that is in direct contact with the top surface of the ferrite mother board" as recited in Applicant's claim 5, and similarly in Applicant's claim 11.

Accordingly, Applicant respectfully requests reconsideration and withdrawal of the rejection of claim 5 under 35 U.S.C. § 103(a) as being unpatentable over AAPA in view of Kubota et al. and Marusawa et al. (U.S. 5,498,999).

Marusawa et al. (JP 9-294006) was relied upon to allegedly cure deficiencies of AAPA and Kubota et al. and Marusawa et al. (U.S. 5,498,999). However, Marusawa et al. (JP 9-294006) clearly fails to teach or suggest the features of "the plurality of center-electrode patterns and the plurality of insulating films are alternately deposited such that each of the plurality of center electrode patterns includes a portion that is in direct contact with a respective one of the plurality of insulating films and another portion that is in direct contact with the top surface of the ferrite mother board" as recited in Applicant's claim 5, and similarly in Applicant's claim 11.

Accordingly, Applicant respectfully submits that AAPA, Kubota et al., Marusawa et al. (U.S. 5,498,999) and Marusawa et al. (JP 9-294006), applied alone or in combination, fail to teach or suggest the unique combination of features and method steps recited in Applicant's claims 5 and 11.

In view of the foregoing amendments and remarks, Applicant respectfully submits that claims 5 and 11 are allowable. Claims 2-4 and 6-9 depend upon claim 5, and are therefore allowable for at least the reasons that claim 5 is allowable. Claims 12-18 depend upon claim 11, and are therefore allowable for at least the reasons that claim 11 is allowable.

Applicant further submits that claim 5 is generic. Since claim 9 depends upon generic claim 5, Applicant respectfully requests that the Examiner rejoin and allow claim 9 when claim 5 is allowed.

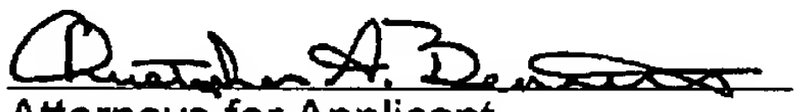
In view of the foregoing amendments and remarks, Applicant respectfully submits that this application is in condition for allowance. Favorable consideration and prompt

allowance are solicited.

The Commissioner is authorized to charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 50-1353.

Respectfully submitted,

Date: August 16, 2004



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